



Device Material Content

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Package: 256 ftBGA
Total Device Weight 0.705 Grams

Package Code:

FTN256 (v.1)

Products:

LC4kV/ZC

Assembly: ASEM
Size (mm): 17 x 17
Lead pitch (mm): 1.0
MSL: 3

Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.001%	0.0071	1.001%	0.0071	Silicon chip	7440-21-3	100.00%	
Mold Compound	55.313%	0.390	48.675% 2.766% 2.766% 0.968% 0.138%	0.3432 0.0195 0.0195 0.0068 0.0010	Silica Fused Epoxy Resin Phenol Resin Metal Hydroxide Carbon Black	60676-86-0 - - - 1333-86-4	88.00% 5.00% 5.00% 1.75% 0.25%	Mold Compound: Sumitomo EME-G770HJ
D/A Epoxy	0.156%	0.0011	0.129% 0.009% 0.009% 0.009% 0.001%	0.00091 0.00006 0.00006 0.00006 0.00001	Silver (Ag) 2,2-dimethyl-1,3 Propanediyl Bismethacrylate A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol 2-[[2,2 bis[[1-(oxoallyloxy)methyl]butoxy]methyl]-2-ethyl-1,3-propanediyl diacrylate bis(4-tert-butylcyclohexyl) peroxydicarbonate	7440-22-4 1985-51-9 - 94108-97-1 15520-11-3	82.43% 5.67% 5.67% 5.67% 0.57%	Die attach epoxy: Henkel (Ablebond) ABL2100A
Wire	1.065%	0.0075	1.065%	0.0075	Gold (Au)	7440-57-5	100.00%	0.8 to 1.0 mil diameter; 1 wire per package lead
Solder Balls	13.779%	0.0971	13.296% 0.413% 0.069%	0.0937 0.0029 0.0005	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	96.50% 3.00% 0.50%	SAC305
Substrate	13.112%	0.0924	4.196% 8.916%	0.0296 0.0629	BT Resins Glass fiber	- 65997-17-3	32.00% 68.00%	BT Resin CCL-HL832NX-A
Foil	9.564%	0.0674	8.144% 1.365% 0.055%	0.0574 0.0096 0.0004	Copper Nickel Gold	7440-50-8 7440-02-0 7440-57-5	85.15% 14.28% 0.57%	
Solder Mask	6.010%	0.0424	3.377% 0.962% 1.322% 0.180% 0.168%	0.0238 0.0068 0.0093 0.0013 0.0012	Quartz 3-methoxy-3-methylbutylacetate Barium Sulfate Talc (containing no asbestiform fibers) Trade secret ingredients	14808-60-7 103429-90-9 7727-43-7 14807-96-6 -	56.20% 16.00% 22.00% 3.00% 2.80%	Solder mask PSR4000 AUS 308
	100.00%	0.705	100.000%	0.705				

Notes:

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